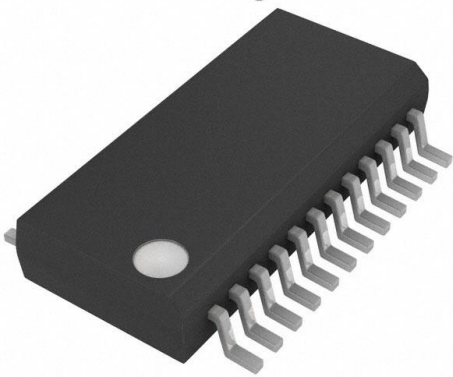


SN74CBTS3384DBQR Datasheet

www.digi-electronics.com



<https://www.DiGi-Electronics.com>

DiGi Electronics Part Number	SN74CBTS3384DBQR-DG
Manufacturer	Texas Instruments
Manufacturer Product Number	SN74CBTS3384DBQR
Description	IC BUS SWITCH 5 X 1:1 24SSOP
Detailed Description	Bus Switch 5 x 1:1 24-SSOP



Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com

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Purchase and inquiry

Manufacturer Product Number:

SN74CBTS3384DBQR

Series:

74CBTS

Type:

Bus Switch

Independent Circuits:

2

Voltage Supply Source:

Single Supply

Operating Temperature:

-40°C ~ 85°C

Package / Case:

24-SSOP (0.154", 3.90mm Width)

Base Product Number:

74CBTS3384

Manufacturer:

Texas Instruments

Product Status:

Obsolete

Circuit:

5 x 1:1

Current - Output High, Low:

-

Voltage - Supply:

4.5V ~ 5.5V

Mounting Type:

Surface Mount

Supplier Device Package:

24-SSOP

Environmental & Export classification

RoHS Status:

ROHS3 Compliant

REACH Status:

REACH Unaffected

HTSUS:

8542.39.0001

Moisture Sensitivity Level (MSL):

2 (1 Year)

ECCN:

EAR99

SN74CBTS3384 10-BIT FET BUS SWITCH WITH SCHOTTKY DIODE CLAMPING

SCDS024M – MAY 1995 – REVISED JULY 2003

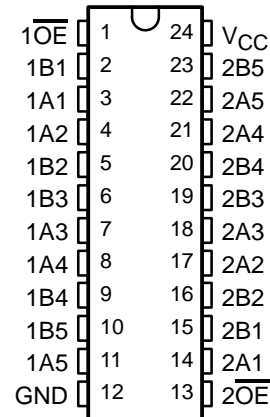
- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels

description/ordering information

The SN74CBTS3384 provides ten bits of high-speed TTL-compatible bus switching with Schottky diodes on the I/Os to clamp undershoot. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device is organized as two 5-bit bus switches with separate output-enable (\overline{OE}) inputs. When \overline{OE} is low, the switch is on, and port A is connected to port B. When \overline{OE} is high, the switch is open, and the high-impedance state exists between the two ports.

DB, DBQ, DGV, DW, OR PW PACKAGE
(TOP VIEW)



ORDERING INFORMATION

TA	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	SOIC – DW	Tube	SN74CBTS3384DW	CBTS3384
		Tape and reel	SN74CBTS3384DWR	
	SSOP – DB	Tape and reel	SN74CBTS3384DBR	CR384
	SSOP (QSOP) – DBQ	Tape and reel	SN74CBTS3384DBQR	CBTS3384
	TSSOP – PW	Tube	SN74CBTS3384PW	CR384
		Tape and reel	SN74CBTS3384PWR	
TVSOP – DGV	Tape and reel	SN74CBTS3384DGV	CR384	

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE
(each 5-bit bus switch)

INPUTS		INPUTS/OUTPUTS	
$\overline{1OE}$	$\overline{2OE}$	1B1–1B5	2B1–2B5
L	L	1A1–1A5	2A1–2A5
L	H	1A1–1A5	Z
H	L	Z	2A1–2A5
H	H	Z	Z



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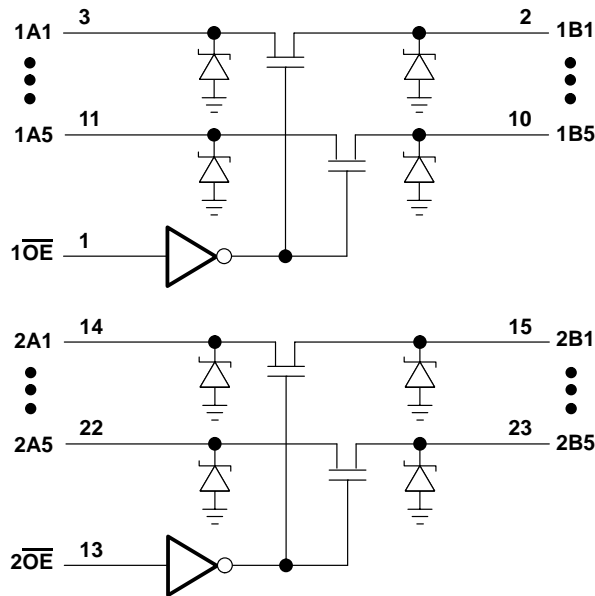
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SN74CBTS3384**10-BIT FET BUS SWITCH****WITH SCHOTTKY DIODE CLAMPING**

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logic diagram (positive logic)**absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†**

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_{I/O} < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2):	
DB package	63°C/W
DBQ package	61°C/W
DGV package	86°C/W
DW package	46°C/W
PW package	88°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
V_{CC} Supply voltage	4	5.5	V
V_{IH} High-level control input voltage	2		V
V_{IL} Low-level control input voltage		0.8	V
T_A Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

SN74CBTS3384
10-BIT FET BUS SWITCH
WITH SCHOTTKY DIODE CLAMPING
 SCDS024M – MAY 1995 – REVISED JULY 2003

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP†	MAX	UNIT	
V _{IK}	A or B inputs	V _{CC} = 4.5 V,	I _I = -18 mA			-0.6	V	
	Control inputs					-1.2		
I _I	I _{IL}	V _{CC} = 5.5 V,	V _I = GND			-1	μA	
	I _{IH}	V _{CC} = 5.5 V,	V _I = 5.5 V			150		
I _{CC}		V _{CC} = 5.5 V,	I _O = 0, V _I = V _{CC} or GND			3	μA	
ΔI _{CC} ‡	Control inputs	V _{CC} = 5.5 V,	One input at 3.4 V, Other inputs at V _{CC} or GND			2.5	mA	
C _i	Control inputs	V _I = 3 V or 0				6	pF	
C _{io(OFF)}		V _O = 3 V or 0,	\overline{OE} = V _{CC}			6.5	pF	
r _{on} §		V _{CC} = 4 V, TYP at V _{CC} = 4 V	V _I = 2.4 V, I _I = 15 mA			14	20	Ω
		V _{CC} = 4.5 V	V _I = 0			5	7	
				I _I = 64 mA			5	
			V _I = 2.4 V, I _I = 15 mA			10	15	

† All typical values are at V_{CC} = 5 V (unless otherwise noted), T_A = 25°C.

‡ This is the increase in supply current for each input that is at the specified TTL voltage level, rather than V_{CC} or GND.

§ Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lowest voltage of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4 V		V _{CC} = 5 V ± 0.5 V		UNIT
			MIN	MAX	MIN	MAX	
t _{pd} ¶	A or B	B or A		0.35		0.25	ns
t _{en}	\overline{OE}	A or B		6.2	1.9	5.7	ns
t _{dis}	\overline{OE}	A or B		5.5	2.1	5.2	ns

¶ The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

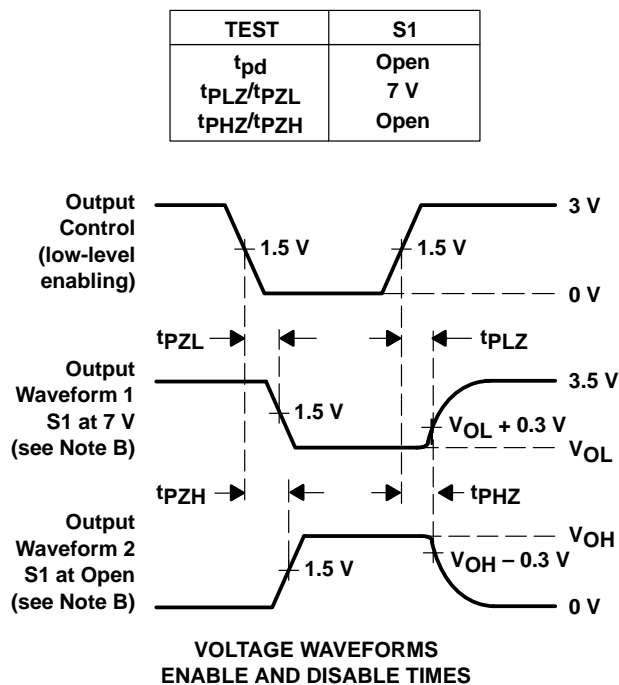
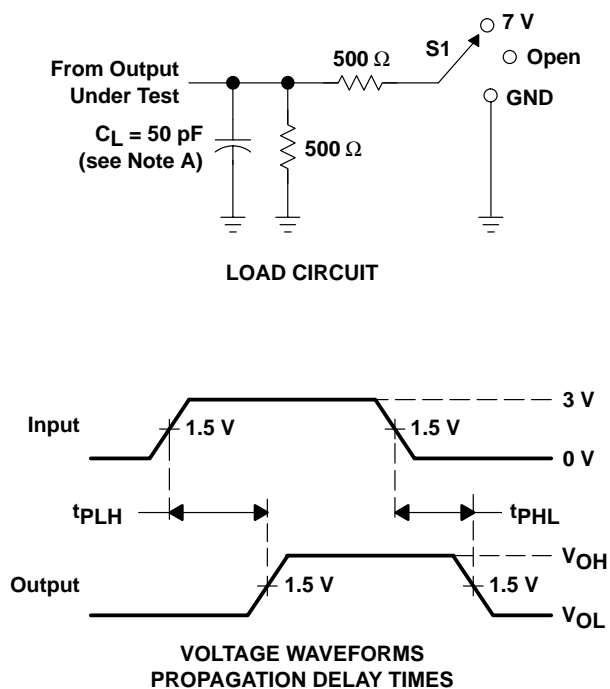
SN74CBTS3384

10-BIT FET BUS SWITCH

WITH SCHOTTKY DIODE CLAMPING

SCDS024M – MAY 1995 – REVISED JULY 2003

PARAMETER MEASUREMENT INFORMATION



- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
 - The outputs are measured one at a time with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis}.
 - t_{PZL} and t_{PZH} are the same as t_{en}.
 - t_{PLH} and t_{PHL} are the same as t_{pd}.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74CBTS3384PW	NRND	TSSOP	PW	24	60	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CR384	
SN74CBTS3384PWR	ACTIVE	TSSOP	PW	24	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CR384	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

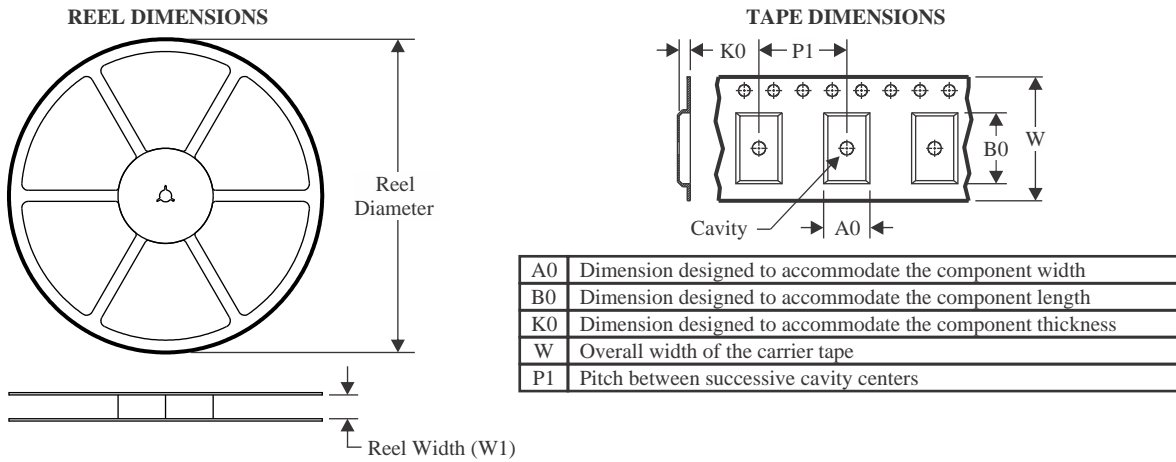
(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

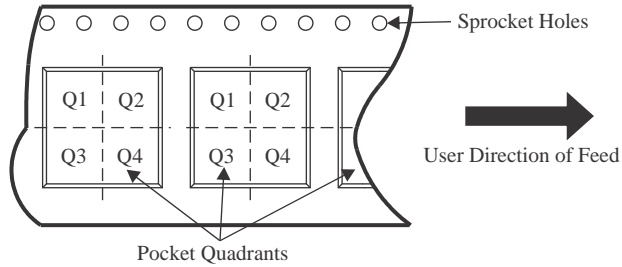
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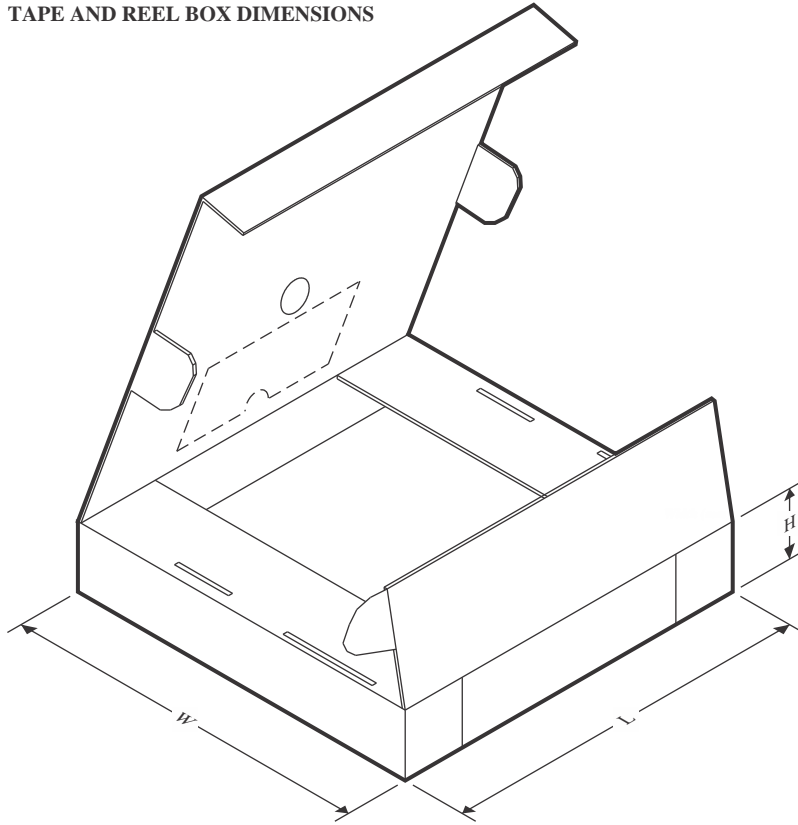
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74CBTS3384PWR	TSSOP	PW	24	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1

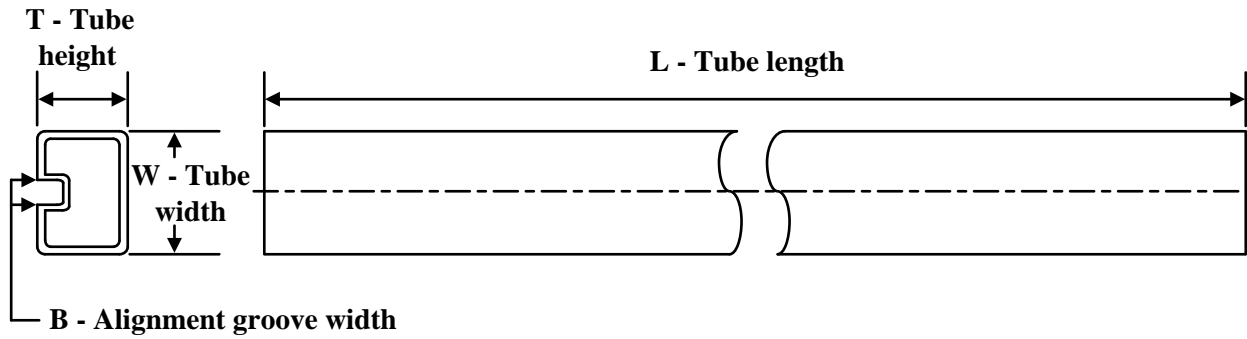
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

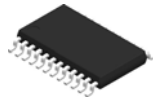
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74CBTS3384PWR	TSSOP	PW	24	2000	356.0	356.0	35.0

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
SN74CBTS3384PW	PW	TSSOP	24	60	530	10.2	3600	3.5

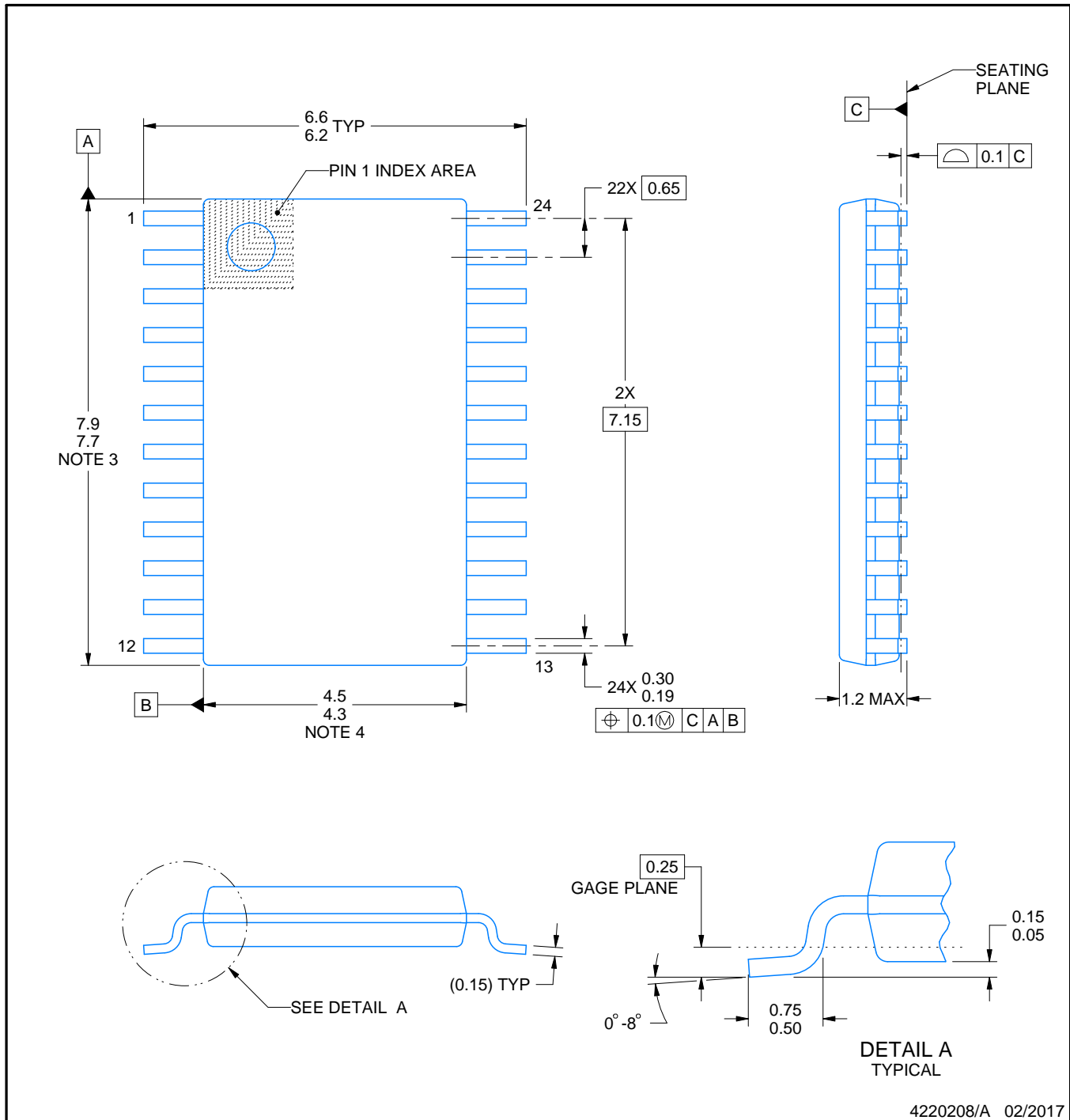


PACKAGE OUTLINE

PW0024A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE

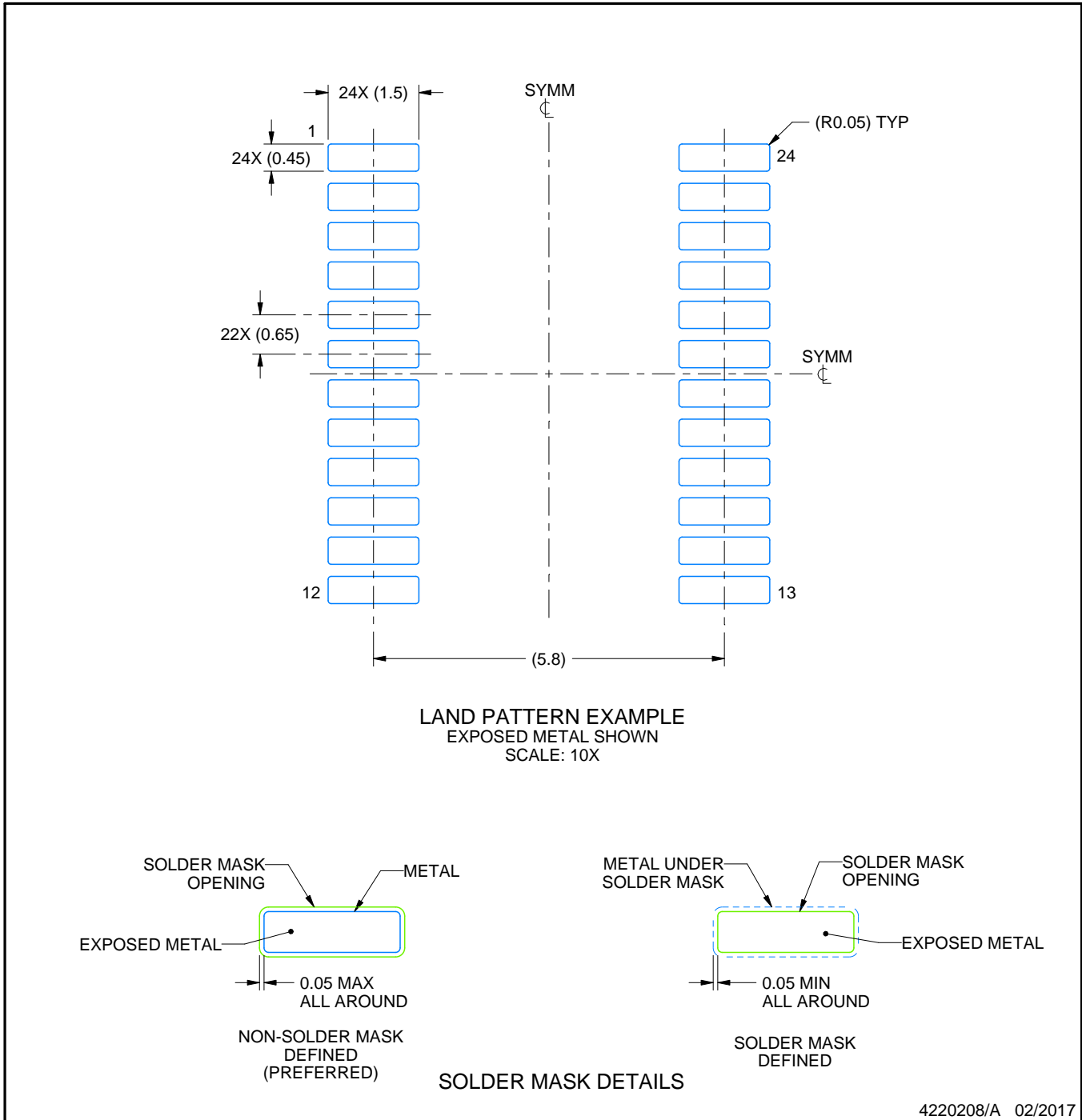


EXAMPLE BOARD LAYOUT

PW0024A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



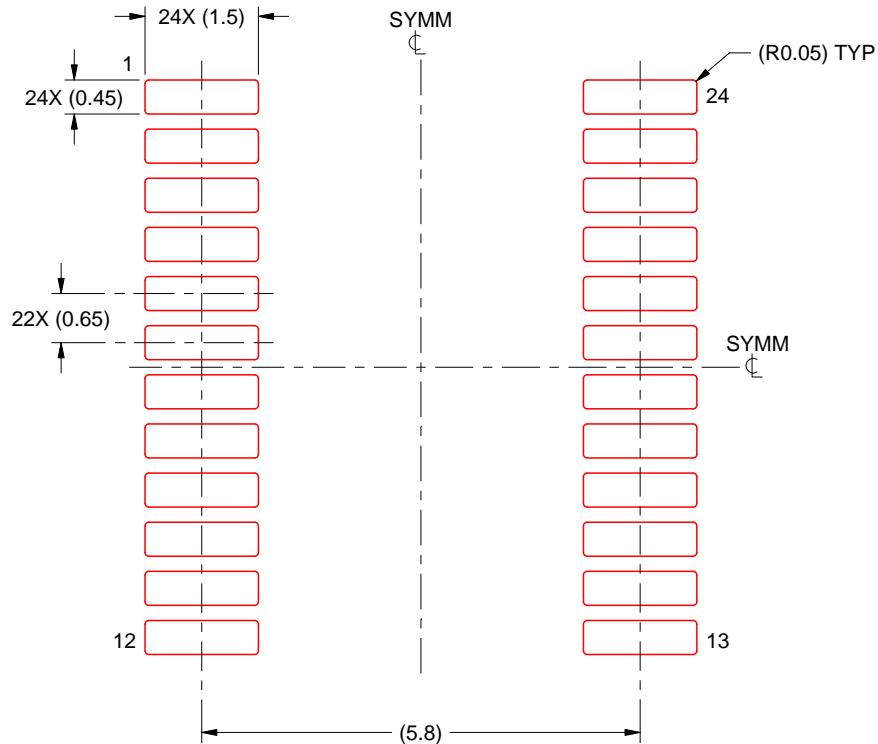
4220208/A 02/2017

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN**PW0024A****TSSOP - 1.2 mm max height**

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
 BASED ON 0.125 mm THICK STENCIL
 SCALE: 10X

4220208/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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